MATERIAL DECLARATION SHEET

Material Number	CDSOT236-0504C		
Product Line	Semiconductor Products		
Compliance Date	**2015/8/28**		
RoHS Compliant	**Yes**	MSL	**3**

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.5000	Silicon	7440-21-3	100.00%	3.125%	3.125%
2	Lead frame	Copper Alloy	3.3353	Copper	7440-50-8	95.29%	20.846%	21.876%
			0.0875	Iron	7439-89-6	2.50%	0.547%	
			0.0035	phosphorous	7723-14-0	0.10%	0.022%	
			0.0035	Zinc	7440-66-6	0.10%	0.022%	
			0.0700	Lead*	7439-92-1	2.00%	0.438%	
			0.0002	Silver	7440-22-4	0.01%	0.001%	
3	Epoxy	Polymer	0.4200	Si-oxide Quartz	14808-60-7	42.00%	2.625%	6.251%
			0.4000	Epoxy resin	Confidential	40.00%	2.500%	
			0.1500	Epoxy resin modifier	Confidential	15.00%	0.938%	
			0.0300	Aromatic amine	Confidential	3.00%	0.188%	
4	Wire	Noble metal	0.9999	Gold	7440-57-5	99.99%	6.2494%	6.25%
			0.0001	Misc, not to declare	/	0.01%	0.0006%	
5	Mold Compound	Polymer	0.7200	Solid Epoxy Resin	Confidential	8.00%	4.500%	56.248%
			0.7200	Phenol Resin	Confidential	8.00%	4.500%	
			7.4970	Fused Silica*1	60676-86-0	83.30%	46.854%	
			0.0450	Carbon Black	1333-86-4	0.50%	0.281%	
			0.0180	Metal Hydroxide	Confidential	0.20%	0.113%	

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society

6	Plating	Plating	0.9999	Tin	7440-31-5	99.99%	6.249%	6.25%
			0.0001	Misc., not to declare	/	0.01%	0.001%	
		Total weight	**16 mg**					

This Document was updated on: 2015/10/28

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. * 6c – copper alloy containing up to 4% lead by weight.